

40W - 28V - 1GHz

**GOLD METALIZED MULTI-PURPOSE
SILICON DMOS RF FET**

FEATURES

- METAL GATE
- EXTRA LOW C_{rss}
- BROAD BAND
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN

APPLICATIONS

- HF/VHF/UHF COMMUNICATIONS
from DC to 1GHz

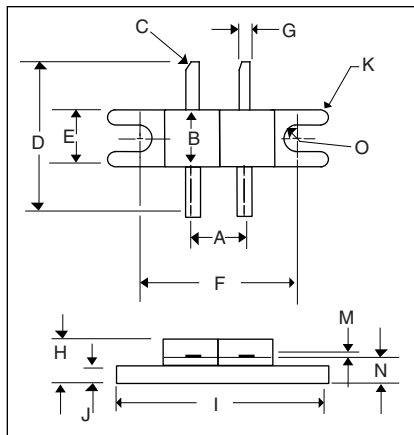
ABSOLUTE MAXIMUM RATINGS
($T_{CASE} = 25^{\circ}C$ unless otherwise stated)

P_D	Power Dissipation	175W
BV_{DSS}	Drain-source breakdown voltage	65V
V_{GS}	Gate-source voltage	$\pm 20V$
I_D	Drain Current	16A
T_{stg}	Storage temperature	-65 to 150°C
T_j	Maximum operating junction temperature	200°C
$R_{THj-case}$	Thermal resistance junction-case	Max. 1.0°C/W

ELECTRICAL CHARACTERISTICS ($T_{CASE} = 25^{\circ}C$ unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<u>PER SIDE</u>					
BV_{DSS}	Breakdown voltage, drain source $V_{GS}=0$ $I_D=50mA$	65			Vdc
I_{DSS}	Drain leakage current $V_{DS}=28V$ $V_{GS}=0$			2	mAdc
I_{GSS}	Gate leakage current $V_{GS}=20V$ $V_{DS}=0$			1	μ Adc
$V_{GS(th)}$	Gate threshold voltage $I_D=10mA$ $V_{DS}=V_{GS}$	1		7	Vdc
g_{fs}	Transconductance (300 μ s pulse) $V_{DS}=10V$ $I_D=1.6A$	1.4			Mhos
<u>TOTAL DEVICE</u>					
G_{PS}	Common source power gain $P_O=40W$	10			dB
η	Drain efficiency $V_{DS}=28V$ $I_{DQ}=1.6A$	40			%
VSWR	Load mismatch tolerance $f=1GHz$	10:1			
<u>PER SIDE</u>					
C_{iss}	Input capacitance $V_{DS}=0V$ $V_{GS}=-5V$ $f=1MHz$			96	pF
C_{oss}	Output capacitance $V_{DS}=28V$ $V_{GS}=0$ $f=1MHz$			40	pF
C_{rss}	Reverse transfer capacitance $V_{DS}=28V$ $V_{GS}=0$ $f=1MHz$			3	pF

DIMENSIONS



DM	Millimeter	TOL	Inches	TOL
A	6.45	.13	.254	.005
B	6.35	.13	.250	.005
C	45°	5°	45°	5°
D	16.51	.76	.650	.030
E	6.48	.13	.255	.005
F	18.42	.13	.725	.005
G	1.52	.13	.060	.005
H	4.83	.03	.160	.010
I	24.77	.13	.975	.005
J	1.52	.13	.060	.001
K	0.81R	.13	.032R	.005
M	.013	.02	.005	.001
N	2.16	.13	.085	.005
O	1.65R	.01	.065R	.005

HAZARDOUS MATERIAL WARNING

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area. THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.

U.S. PATENTS 5,121,176 & 5,179,032
GLOBAL PATENTS PENDING

*C202

*PSPICE MODEL FOR POINT NINE RF N-CHANNEL VERTICAL DMOS POWER FET

*May 2004

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*          _____ GATE
*          I   _____ DRAIN
*          I   I   _____ SOURCE
*          I   I   I
.SUBCKT C202  10  20  30
*Cin1,Cin2 & Lin model the input side of the package
Cin1  10  30  0.4p
Lin   10  11  0.3n
Cin2  11  30  0.4p

LG    11  12  0.5n   ;Gate bond wire inductance
CGS   12  13  84.8p  ;Gate-source capacitance
MOS   14  12  13     13  C202 L=0.9U W=0.0872   ;D G S B LEVEL1
JFET  16  13  14     C202                       ;D G S
DBODY 13  16  C202                               ;P N
LS    13  30  0.15n ;Source bond wire inductance
CGD   12  16  2.4p  ;Gate-drain feedback capacitance

*Cout1,Cout2 & Lout model the output side of the package
Cout1 16  30  0.9p
Lout   16  20  0.5n
Cout2 20  30  0.65p

.MODEL C202 NMOS (VTO=3.52 KP=7.77E-4 LAMBDA=0.0224 RD=0.08 RS=0.34)
.MODEL C202 NJF  (VTO=-5.8 BETA=0.2928 LAMBDA=1.357)
.MODEL C202 D    (CJO=120P RS=0.25 VJ=0.7 M=0.33 BV=70)

.ENDS
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